



P-Channel Enhancement Mode Power MOSFET

Description

The PED2015M uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

General Features

- $V_{DS} = -20V$, $I_D = -40A$

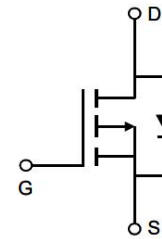
$R_{DS(ON)} < 11m\Omega @ V_{GS}=-4.5V$

$R_{DS(ON)} < 15m\Omega @ V_{GS}=-2.5V$

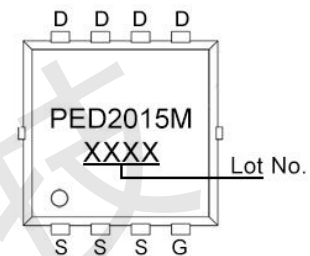
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

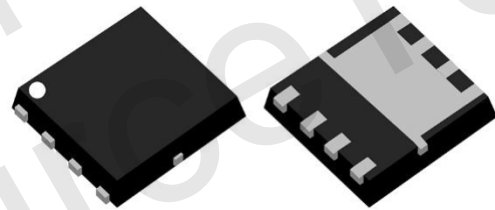
- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



PDFN3.3x3.3-8L

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

| Parameter | Symbol | Rating | Unit |
|--|----------------|------------|------|
| Drain-Source Voltage | V_{DS} | -20 | V |
| Gate-Source Voltage | V_{GS} | ± 12 | V |
| Drain Current-Continuous | I_D | -40 | A |
| Drain Current-Continuous (TC=100°C) | I_D | -27 | A |
| Pulsed Drain Current (Note 1) | I_{DM} | -100 | A |
| Avalanche Current | I_{AS} | -22 | A |
| Avalanche Energy (L=0.5mH) | E_{AS} | 121 | mJ |
| Maximum Power Dissipation | P_D | 29 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | °C |

Thermal Characteristic

| | | | |
|--------------------------------------|-----------------|-----|------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 4.3 | °C/W |
|--------------------------------------|-----------------|-----|------|



Electrical Characteristics (TC=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|--------------|---|------|------|-----------|------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=-250\mu A$ | -20 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=-20V, V_{GS}=0V$ | - | - | -1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 12V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -0.4 | -0.7 | -1 | V |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS}=-4.5V, I_D=-7A$ | - | 8.5 | 11 | m Ω |
| | | $V_{GS}=-2.5V, I_D=-5A$ | - | 11 | 15 | m Ω |
| sForward Transconductance | g_{FS} | $V_{DS}=-5V, I_D=-10A$ | - | 38 | - | S |
| Dynamic Characteristics (Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=-10V, V_{GS}=0V,$ $F=1.0MHz$ | - | 3650 | - | pF |
| Output Capacitance | C_{oss} | | - | 520 | - | pF |
| Reverse Transfer Capacitance (Note 4) | C_{rss} | | - | 370 | - | pF |
| Switching Characteristics | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=-10V, R_L=1\Omega,$ $V_{GS}=-10V, R_G=3\Omega$ | - | 15 | - | nS |
| Turn-on Rise Time | t_r | | - | 43 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 158 | - | nS |
| Turn-Off Fall Time | t_f | | - | 90 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=-10V, I_D=-10A,$ $V_{GS}=-4.5V$ | - | 34 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 7 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 9 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | $V_{GS}=0V, I_S=-1A$ | - | - | -1.2 | V |
| Diode Forward Current (Note 2) | I_S | | - | - | -30 | A |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to product.



Typical Electrical and Thermal Characteristics

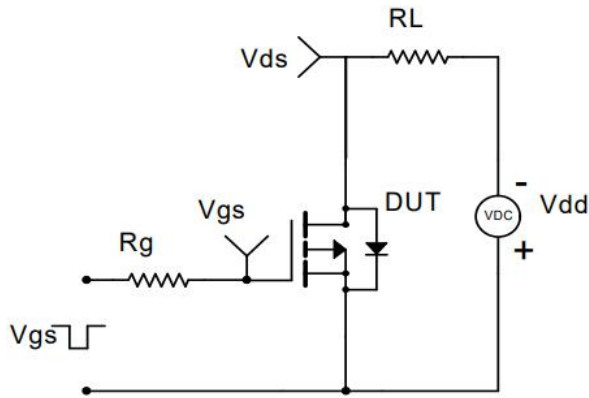


Figure 1 Switching Test Circuit

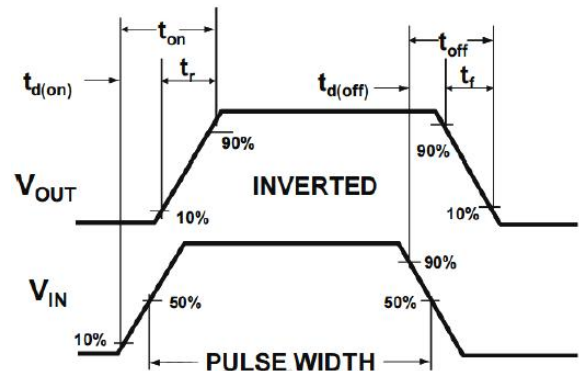


Figure 2 Switching Waveform

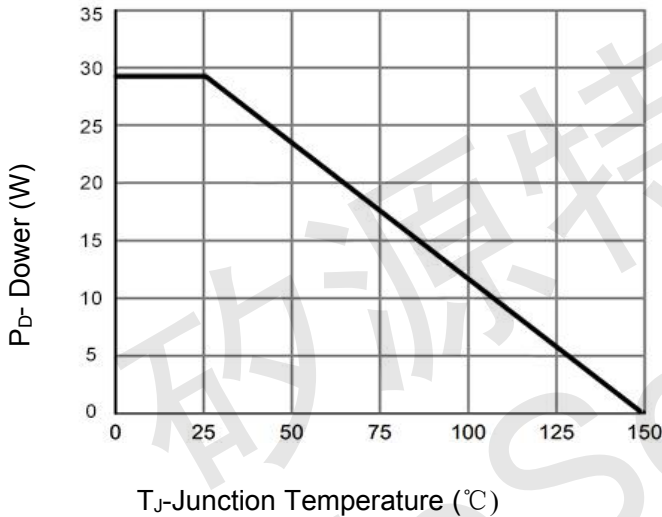


Figure 3 Power De-rating

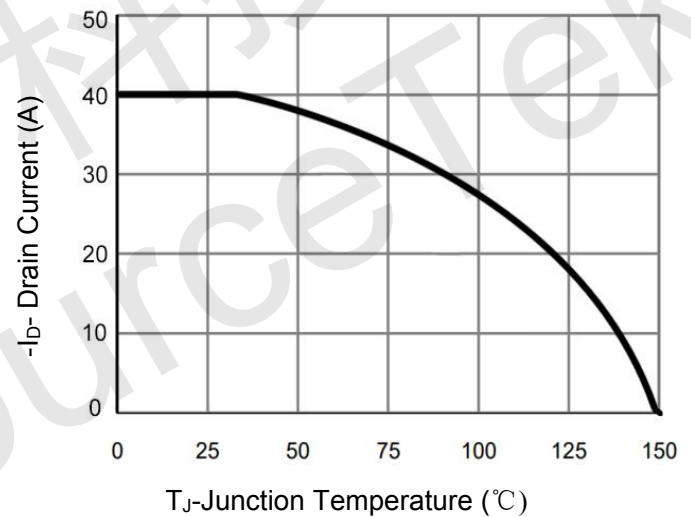


Figure 4 Drain Current

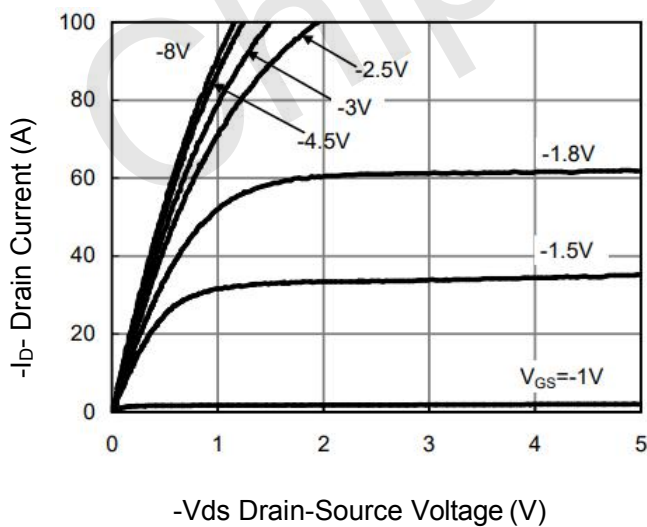


Figure 5 Output Characteristics

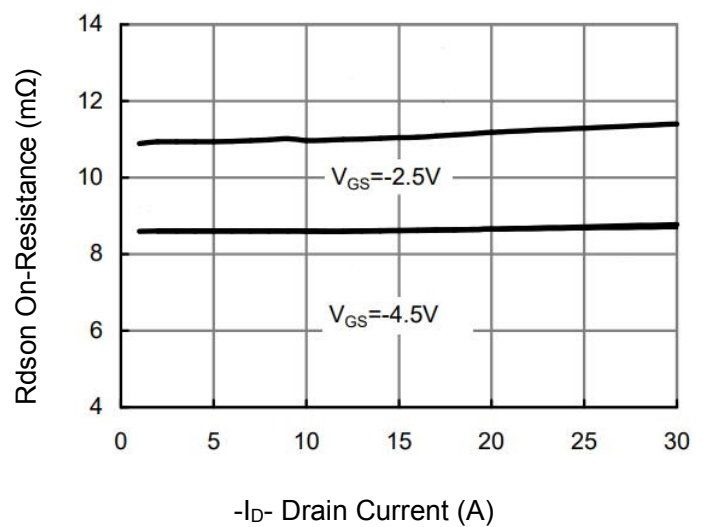


Figure 6 Rds(on) vs Drain Current

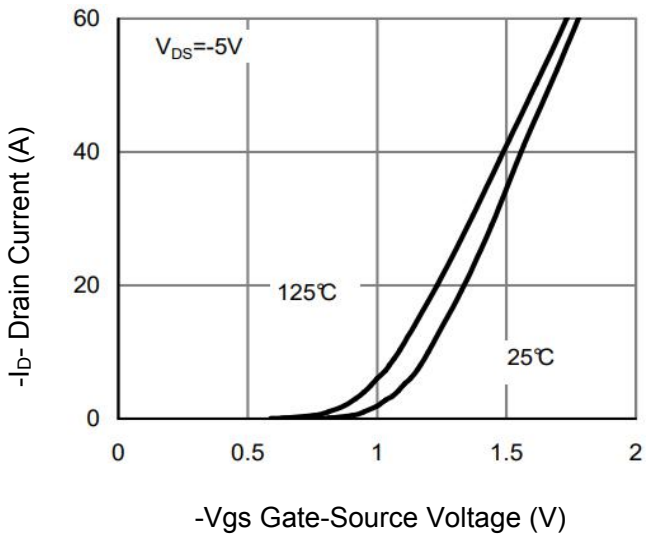


Figure 7 Transfer Characteristics

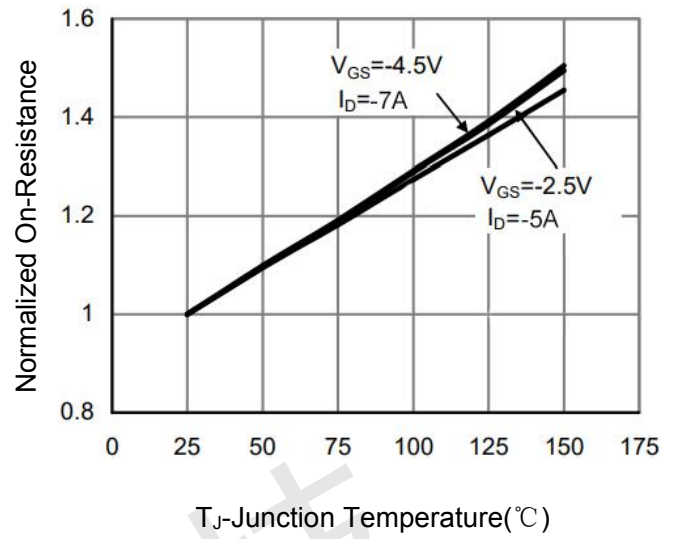


Figure 8 Rdson vs Junction Temperature

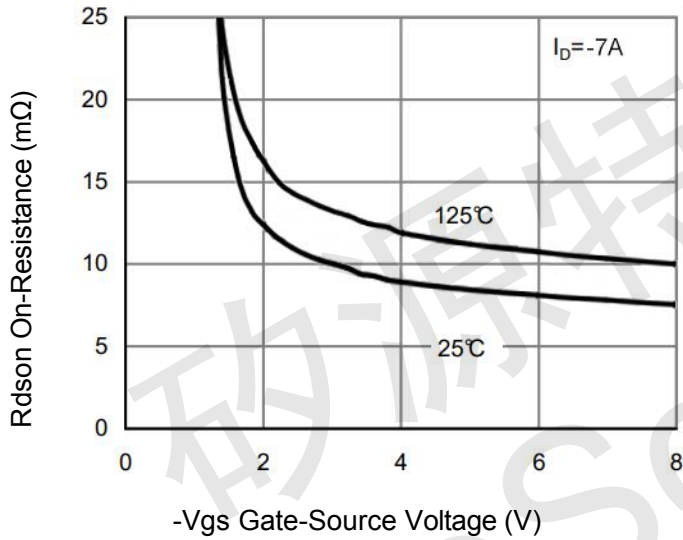


Figure 9 Rdson vs Vgs

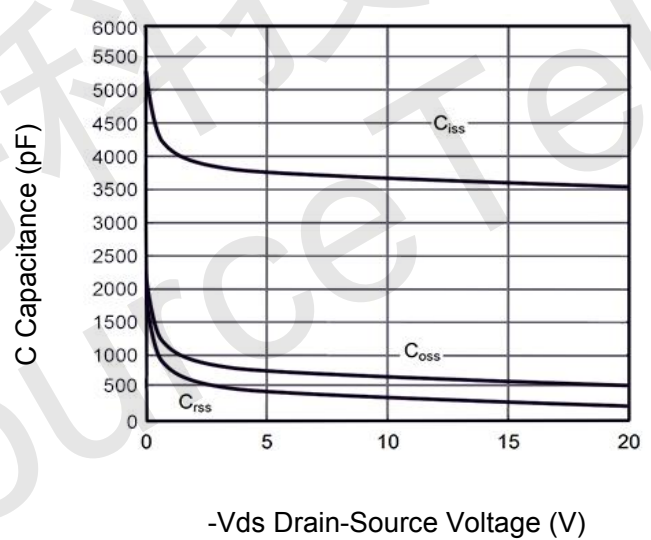


Figure 10 Capacitance vs Vds

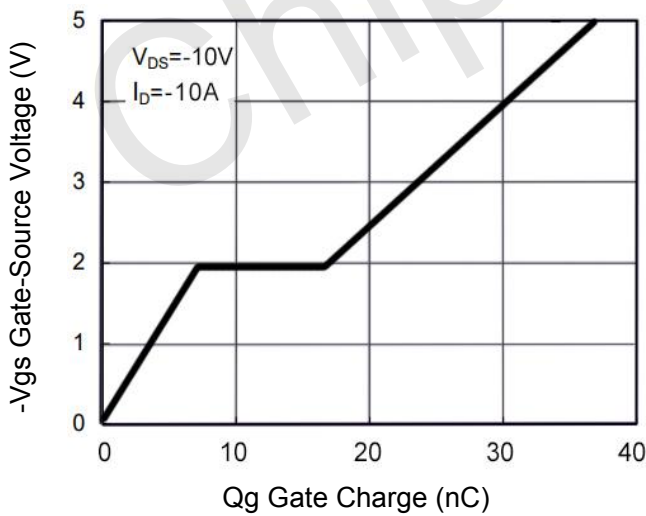


Figure 11 Gate Charge

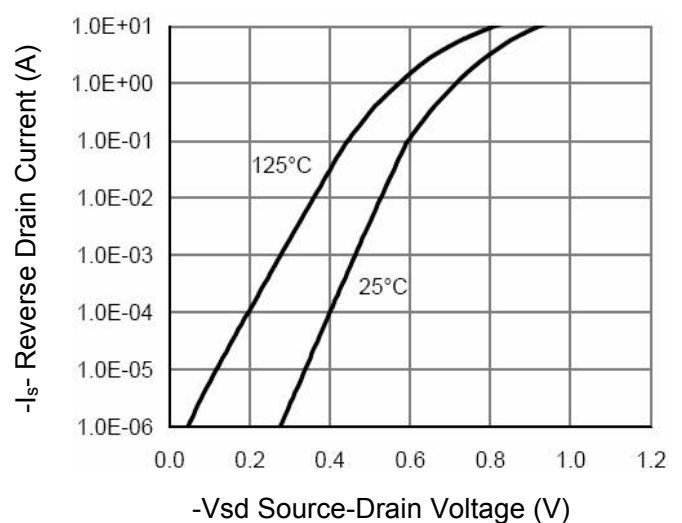


Figure 12 Source- Drain Diode Forward

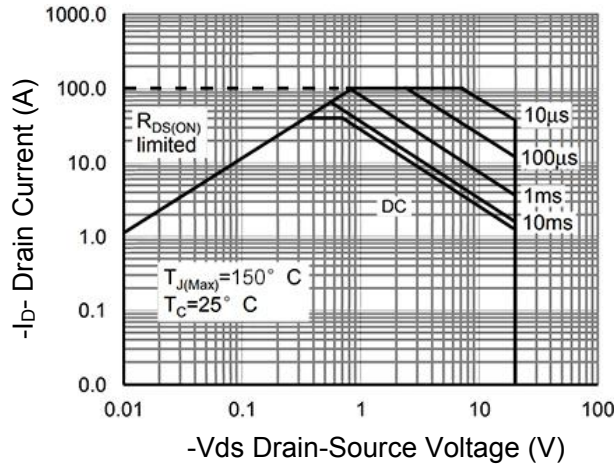


Figure 13 Safe Operation Area

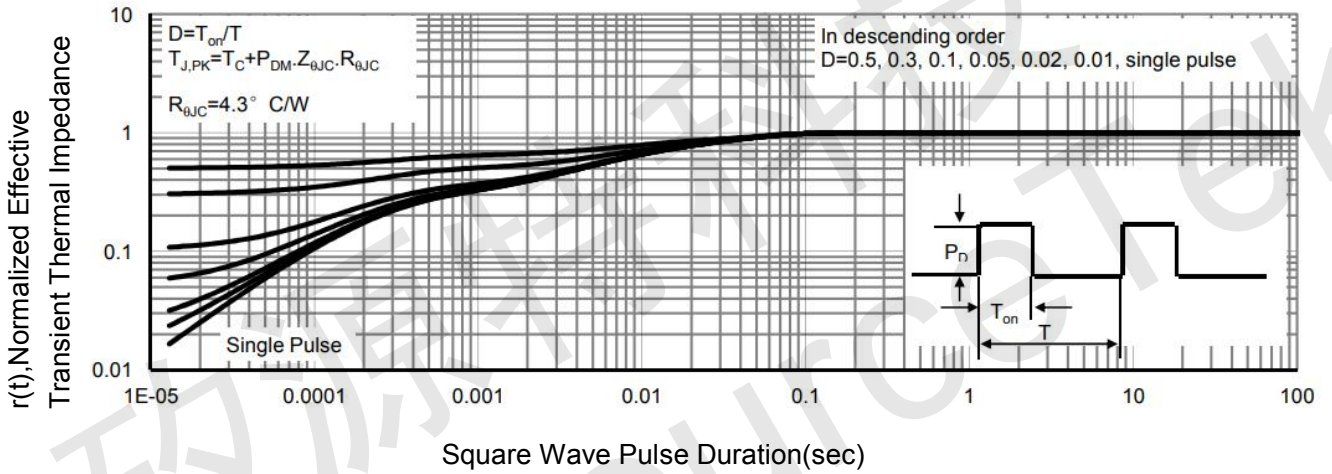
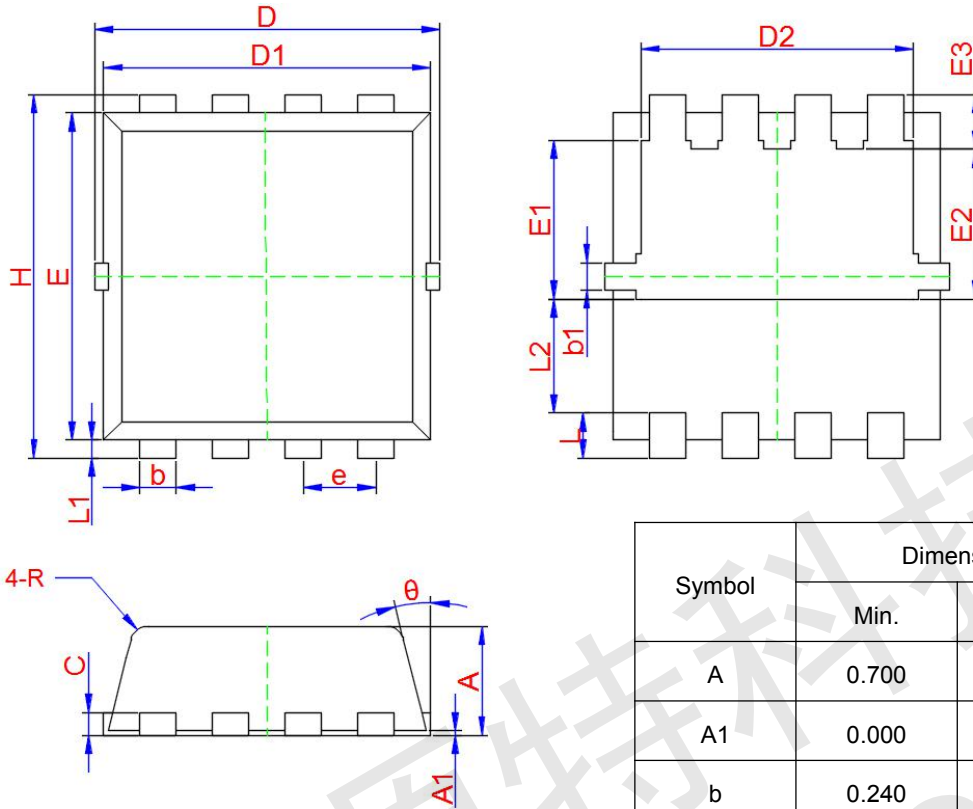


Figure 14 Normalized Maximum Transient Thermal Impedance



PDFN3.3x3.3-8L Package Information



| Symbol | Dimensions In Millimeters | | |
|--------|---------------------------|-------|-------|
| | Min. | Typ. | Max. |
| A | 0.700 | 0.800 | 0.900 |
| A1 | 0.000 | 0.030 | 0.050 |
| b | 0.240 | 0.300 | 0.350 |
| b1 | 0.080 | 0.130 | 0.180 |
| c | 0.152 TYP. | | |
| D | 3.250 | 3.320 | 3.400 |
| D1 | 3.050 | 3.150 | 3.250 |
| D2 | 2.400 | 2.500 | 2.600 |
| E | 3.000 | 3.100 | 3.200 |
| E1 | 1.350 | 1.450 | 1.550 |
| E2 | 1.200 | 1.300 | 1.400 |
| E3 | 0.400 | 0.500 | 0.600 |
| e | 0.650 TYP. | | |
| H | 3.200 | 3.300 | 3.400 |
| L | 0.300 | 0.400 | 0.500 |
| L1 | 0.100 | 0.150 | 0.200 |
| L2 | 1.130 TYP. | | |
| R | 0.200 TYP. | | |
| θ | 6° | 10° | 14° |